

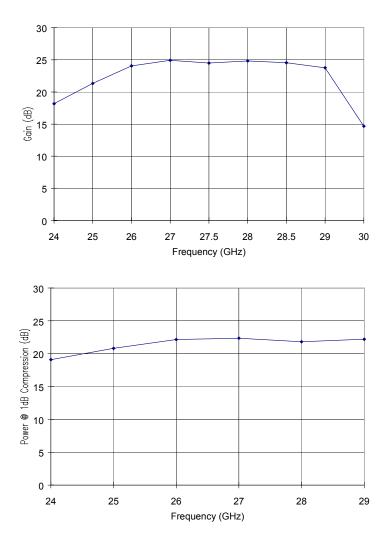
26-29 GHz Medium Power Amplifier TGA1081-EPU

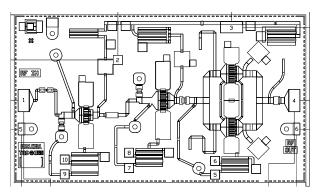
Key Features and Performance

- Production version of TGA9058
- 0.25um pHEMT Technology
- 26 GHz 29 GHz Frequency Range
- Nominal Pout 22dBm @ 1dB GC
- Nominal SS Gain 24dB
- 5V, 315mA Bias

Primary Applications

- LMDS
- Point-to-Point Radio





Chip Dimensions 3.365 mm x 1.971 mm

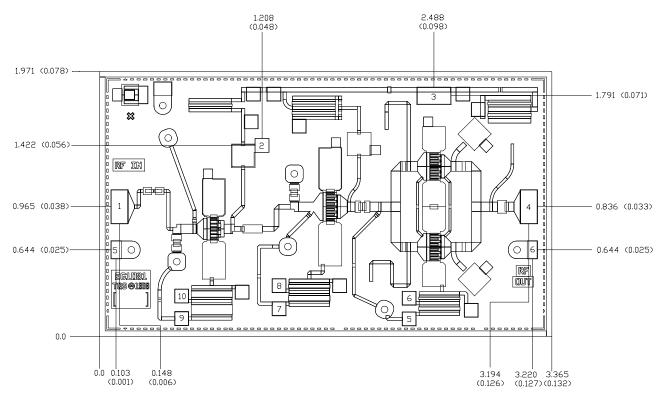
Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications subject to change without notice.

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Advance Product Information

TGA1081



Units: millimeters (inches) Thickness: 0.1016 (0.004) (reference only) Chip edge to bond pad dimensions are shown to center of bond pad Chip size tolerance: +/- 0.0508 (0.002)

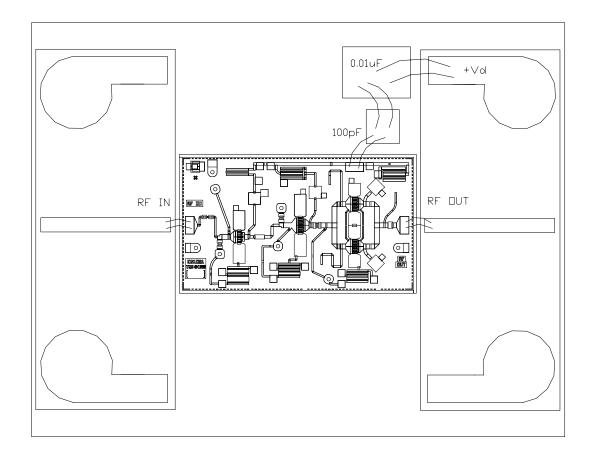
Bond	pad	#1	(RF Input)	0.125	×	0.250	(0.005	×	0.010>
Bond	pad	#2	(Gnd)	0.103	×	0.105	(0.004	×	0.004)
Bond	pad	#3	(Vd)	0.125	×	0.250	(0.005	×	0.010)
Bond	pad	#4	(RF Output)	0.125	×	0.250	(0.005	×	0.010>
Bond	pad	#5	(Gnd)	0.075	×	0.136	(0.003	×	0.005)
Bond	pad	#6	(Gnd)	0.075	×	0.136	(0.003	×	0.005>

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TGA1081



Assembly Diagram

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